NA-1429

BLS6G3135-120 at 3100-3500 MHz

Rev. 2 — 28 April 2015

Application Measurement Report

Document information	n
Info	Content
Keywords	NA-1429
Abstract	Measurement results of a demo board for 3100-3500 MHz with 1x BLS6G3135-120.



Revision history

Rev	Date	Description
1	20111213	
2	20150424	Update for web publication

Contact information

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NA-1429

1. Introduction

1.1 General information

This report gives the test results for a 3100-3500MHz demo amplifier (Board NA-1429), using the NXP LDMOS transistor **BLS6G3135-120**. The following test has been performed:

• Pulsed CW @ V_{DS} =32V, I_{DQ} =100mA, t_p =300 μ s, δ =10%

All testing has been performed at V_{DS} =32V, I_{DQ} =100mA and T_{H} =25°C. Data is presented in graphical format.

NOTE: Use an Electrolytic Capacitor of 10000 μ F parallel to the V_{ds} as close as possible to the demo board. This delivers the current peaks to the demo board.

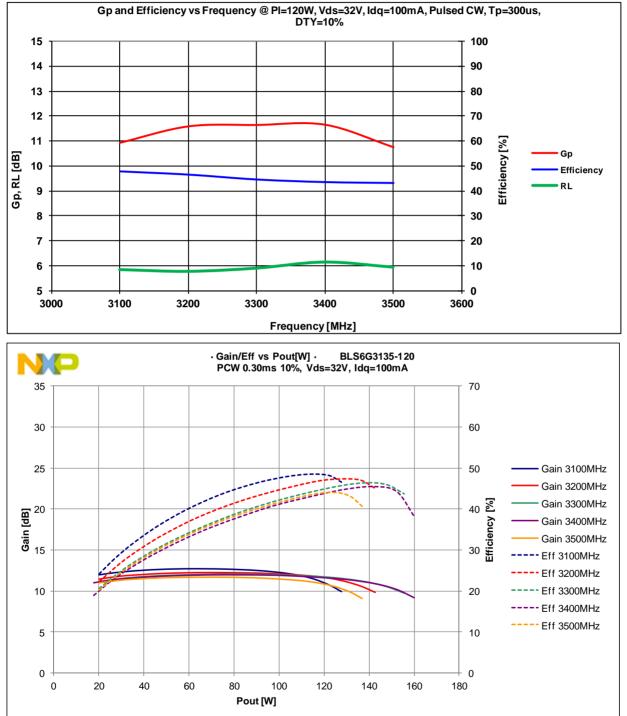
1.2 Test circuit

A description of this circuit can be found in **chapter** Error! Reference source not found.. The est circuit has been designed on Duriod 6006, 0.64mm thick, ε_r =6.16.

Application Measurement Report

2. Measurement Results



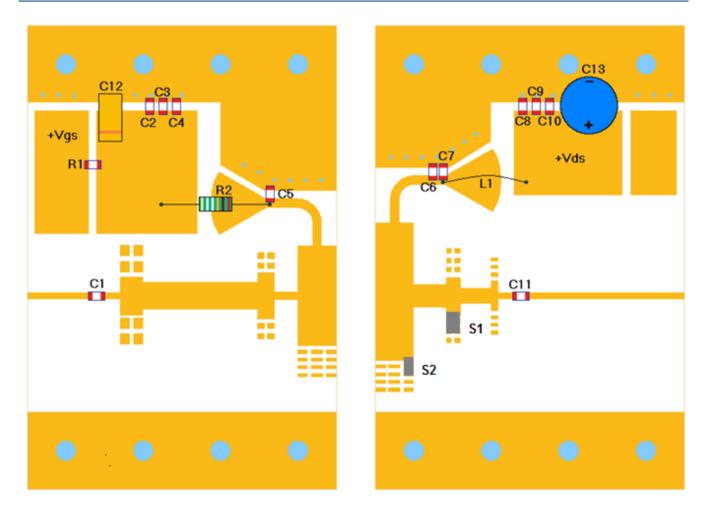


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BLS6G3135-120 at 3100-3500 MHz

NA-1429

3. Test Circuit and List of Components

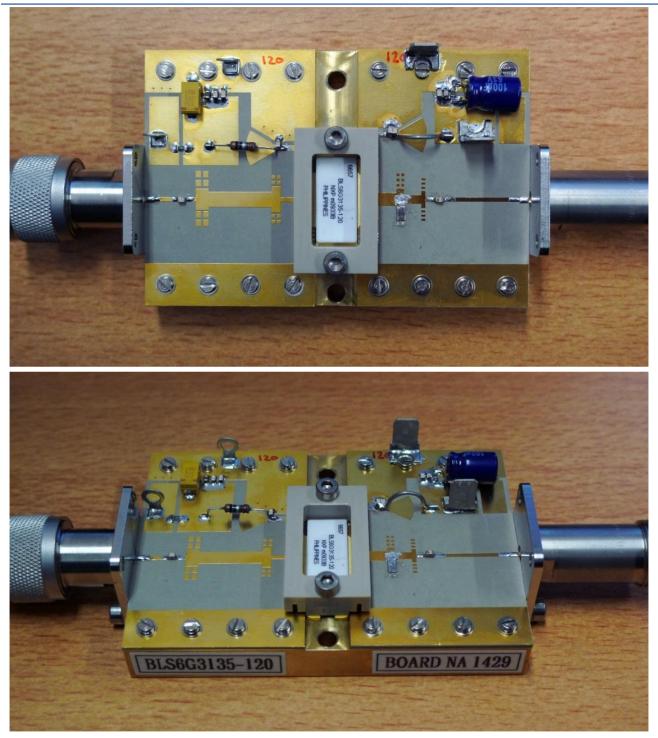


List of components				
Component	Desciption			
C1,C3,C4,C5,C6,C7,C8,C9,C11	24pF ATC100A			
C2,C10	1nF ATC700A			
C12	47uF/20V Tantalum			
C13	100uF/63V			
R1	56 Ohm SMD			
R2	49.9 Ohm / 0.6W MetalFilm			
S1	Metal Strip			
L1	Copper wire 1mm diameter, length=16mm			
Pcb-material=Duriod 6006,E r=6.16, H=0.64mn	n, 2x Cu			

NA-1429

NA-1429 BLS6G3135-120 at 3100-3500 MHz

4. Photos Demo Board



5. Attachments

Please see the attachment for the support files.

NA-1429

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Application Measurement Report

BLS6G3135-120 at 3100-3500 MHz

7. Contents

1.	Introduction	3
1.1	General information	
1.2	Test circuit	3
2.	Measurement Results	4
2.1	Test Results Frequency Sweep and Power	
	Sweep:	4
3.	Test Circuit and List of Components	5
4.	Photos Demo Board	6
5.	Attachments	6
6.	Legal information	
6.1	Definitions	7
6.2	Disclaimers	
6.3	Trademarks	7
7.	Contents	8

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> Date of release: 28 April 2015 Document identifier: NA-1429